

CLMPTO

12/13/04

CM.

1. A method for forming a scribed groove at the surface portion of a wafer by using a cutting part having a cutting edge, the method comprising the step of moving the cutting part such that the cutting edge forms a path having the shape of an inverted trapezoid.
2. A method as defined by claim 1, the method further comprising the steps of:
 - (a) picking up the image of the cutting edge; and
 - (b) based on the picked-up image data, adjusting the angle of the cutting edge against the surface of the wafer.
3. A method as defined by claim 1, the method further comprising the steps of:
 - (a) measuring the thickness of the wafer; and
 - (b) in accordance with the measured thickness, adjusting the entry position of the cutting part into the wafer by combining the horizontal and vertical movements of the cutting part.

4. A method as defined by claim 2, the method further comprising the steps of:

(a) measuring the thickness of the wafer; and

(b) in accordance with the measured thickness, adjusting the entry position of the cutting part into the wafer by combining the horizontal and vertical movements of the cutting part.

CLAIMS 5-8. (CANCELLED)